

MNLM6161-X REV 2A1

 Original Creation Date: 08/03/95
 Last Update Date: 11/23/98
 Last Major Revision Date: 10/28/98

HIGH SPEED OPERATIONAL AMPLIFIER
General Description

The LM6161 high-speed amplifier exhibits an excellent speed-power product in delivering 300 V/uS and 50 MHz unity gain stability with only 5 mA of supply current. Further, power savings and application convenience are possible by taking advantage of the wide dynamic range in operating supply voltage which extends all the way down to +5V.

This amplifier is built with National's VIP[™] (Vertically Integrated PNP) process which provides fast PNP transistors that are true complements to the already fast NPN devices. This advanced junction-isolated process delivers high speed performance without the need for complex and expensive dielectric isolation.

Industry Part Number

LM6161

Prime Die

LM6161B

NS Part Numbers

 LM6161E/883*
 LM6161J-QMLV **
 LM6161J/883 ***
 LM6161W-SMD ****
 LM6161W/883
 LM6161WG-QMLV *****
 LM6161WG/883 *****

Controlling Document

See Features Page

Processing

MIL-STD-883, Method 5004

Quality Conformance Inspection

MIL-STD-883, Method 5005

Subgrp	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

Features

- High slew rate 300V/uS
- High unity gain freq 50MHz
- Low supply current 5mA
- Fast settling 120nS to 0.1%
- Low differential gain <0.1%
- Low differential phase 0.1 degrees
- Wide supply range 4.75V to 32V
- Stable with unlimited capacitive load
- Well behaved; easy to apply
- SMD : 5962-89621012A*,VPA**,PA***,HA****,VXA*****,XA*****

Applications

- Video amplifier
- High-frequency filter
- Wide-bandwidth signal conditioning
- Radar
- Sonar

(Absolute Maximum Ratings)

(Note 1)

Supply Voltage (V+ - V-)	36V
Differential Input Voltage Range (Note 4)	±8V
Common-Mode Voltage Range (Note 6)	(V+ - 0.7V) to (V- - 7V)
Output Short Circuit to Gnd (Note 3)	Continuous
Power Dissipation (Note 2)	400mW
Soldering Information (Soldering, 10 seconds)	260 C
Storage Temperature Range	-65 C to +150 C
Maximum Junction Temperature	150 C
Thermal Resistance	
ThetaJA	
LCC	(Still Air) 90 C/W (500LF/Min Air flow) 61 C/W
CERDIP	(Still Air) 113 C/W (500LF/Min Air flow) 51 C/W
CERPAK	(Still Air) 228 C/W (500LF/Min Air flow) 140 C/W
CERAMIC SOIC	(Still Air) 228 C/W (500LF/Min Air flow) 140 C/W
ThetaJC	
LCC	20 C/W
CERDIP	21 C/W
CERPAK	21 C/W
CERAMIC SOIC	21 C/W
ESD Tolerance (Note 4, 5)	±500V

- Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- Note 2: The maximum power dissipation must be derated at elevated temperatures and is dictated by Tjmax (maximum junction temperature), ThetaJA (package junction to ambient thermal resistance), and TA (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{dmax} = (T_{jmax} - T_A) / \Theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.
- Note 3: Continuous short-circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150 C.
- Note 4: In order to achieve optimum AC performance, the input stage was designed without protective clamps. Exceeding the maximum differential input voltage results in reverse breakdown of the base-emitter junction of one of the input transistors and probable degradation of the input parameters (especially Vio, Iio and Noise).
- Note 5: The average voltage that the weakest pin combinations (those involving Pin 2 or Pin 3) can withstand and still conform to the datasheet limits. The test circuit used consists of the human body model of 100pF in series with 1500 Ohms.
- Note 6: The voltage between V+ and either input pin must not exceed 36V.

Recommended Operating Conditions

(Note 1)

Temperature Range

$-55\text{ C} \leq \text{TA} \leq +125\text{ C}$

Supply Voltage Range

4.75V to 32V

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Electrical Characteristics

DC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)
DC: $V_{cc} = \pm 15V$, $V_{cm} = 0V$, $R_l \geq 100K$ Ohms, $R_s = 10K$ Ohms.

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
Vio	Input Offset Voltage				-7	7	mV	1
					-10	10	mV	2, 3
Iib	Input Bias Current				-3	3	uA	1
					-6	6	uA	2, 3
Iio	Input Offset Current				-350	350	nA	1
					-800	800	nA	2, 3
+Vcmr	Positive Common-Mode Voltage Range	$V_{cc} = \pm 15V$			13.9		V	1
		$V_{cc} = \pm 15V$			13.8		V	2, 3
		$V_{cc} = +5V$	2		3.9		V	1
		$V_{cc} = +5V$	2		3.8		V	2, 3
-Vcmr	Negative Common-Mode Voltage Range	$V_{cc} = \pm 15V$				-12.9	V	1
		$V_{cc} = \pm 15V$				-12.7	V	2, 3
		$V_{cc} = +5V$	2			2.0	V	1
		$V_{cc} = +5V$	2			2.2	V	2, 3
CMRR	Common-Mode Rejection Ratio	$-12.9V \leq V_{cm} \leq 13.9V$			80		dB	1
		$-12.7V \leq V_{cm} \leq 13.8V$			74		dB	2, 3
PSRR	Power Supply Rejection Ratio	$\pm 10V \leq V_{cc} \leq \pm 16V$			80		dB	1
		$\pm 10V \leq V_{cc} \leq \pm 16V$			74		dB	2, 3
Ios	Output Short Circuit Current	Source				-30	mA	1
						-20	mA	2, 3
		Sink			30	mA	1	
					20	mA	2, 3	
Icc	Supply Current				6.5	mA	1	
					6.8	mA	2, 3	
Avs	Large Signal Voltage Gain	$V_{out} = \pm 10V$, $R_l = 2K$ Ohms	1		550		V/V	1
		$V_{out} = \pm 10V$, $R_l = 2K$ Ohms	1		300		V/V	2, 3
+Vop	Positive Voltage Swing	$V_{cc} = \pm 15V$, $R_l = 2K$ Ohms			13.5		V	1
		$V_{cc} = \pm 15V$, $R_l = 2K$ Ohms			13.3		V	2, 3
		$V_{cc} = +5V$, $R_l = 2K$ Ohms			3.5		V	1
		$V_{cc} = +5V$, $R_l = 2K$ Ohms			3.3		V	2, 3

Electrical Characteristics

DC PARAMETERS (Continued)

(The following conditions apply to all the following parameters, unless otherwise specified.)
DC: $V_{cc} = \pm 15V$, $V_{cm} = 0V$, $R_l \geq 100K$ Ohms, $R_s = 10K$ Ohms.

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
-Vop	Negative Voltage Swing	$V_{cc} = \pm 15V$, $R_l = 2K$ Ohms				-13.0	V	1
		$V_{cc} = \pm 15V$, $R_l = 2K$ Ohms				-12.7	V	2, 3
		$V_{cc} = +5V$, $R_l = 2K$ Ohms				1.7	V	1
						2.0	V	2, 3

AC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)
AC: $V_{cc} = \pm 15V$, $V_{cm} = 0V$, $R_l \geq 100K$ Ohms, $R_s = 10K$ Ohms.

Gbw	Gain Bandwidth Product	$f = 20Mhz$			40		Mhz	4
					30		Mhz	5, 6
+Sr	Slew Rate	Output step = -4V to +4V, $A_v = +1$, $V_{in} = 8V$ step			200		V/uS	4
					180		V/uS	5, 6
-Sr	Slew Rate	Output step = +4V to -4V, $A_v = +1$, $V_{in} = 8V$ step			200		V/uS	4
					180		V/uS	5, 6
ts	Setting Time	10V step to 0.1% , $A_v = 1$, $R_l = 2K$ Ohms				300	nS	9
							325	nS

DC PARAMETERS: DRIFT VALUES

(The following conditions apply to all the following parameters, unless otherwise specified.)
DC: $V_{cc} = \pm 15V$, $V_{cm} = 0V$, $R_l \geq 100K$ Ohms, $R_s = 10K$ Ohms. Delta Calculations Performed on QMLV Devices at Group B, Subgroup 5 ONLY.

Vio	Input Offset Voltage				-0.7	+0.7	mV	1
Iib	Input Bias Current				-0.5	+0.5	uA	1
Iio	Input Offset Current				-35	+35	nA	1
CMRR	Common Mode Rejection Ratio	$-12.9V \leq +V_{cm} \leq 13.9V$			-5	+5	dB	1

Note 1: Voltage gain is the total output swing (20V) divided by the signal required to produce that swing.

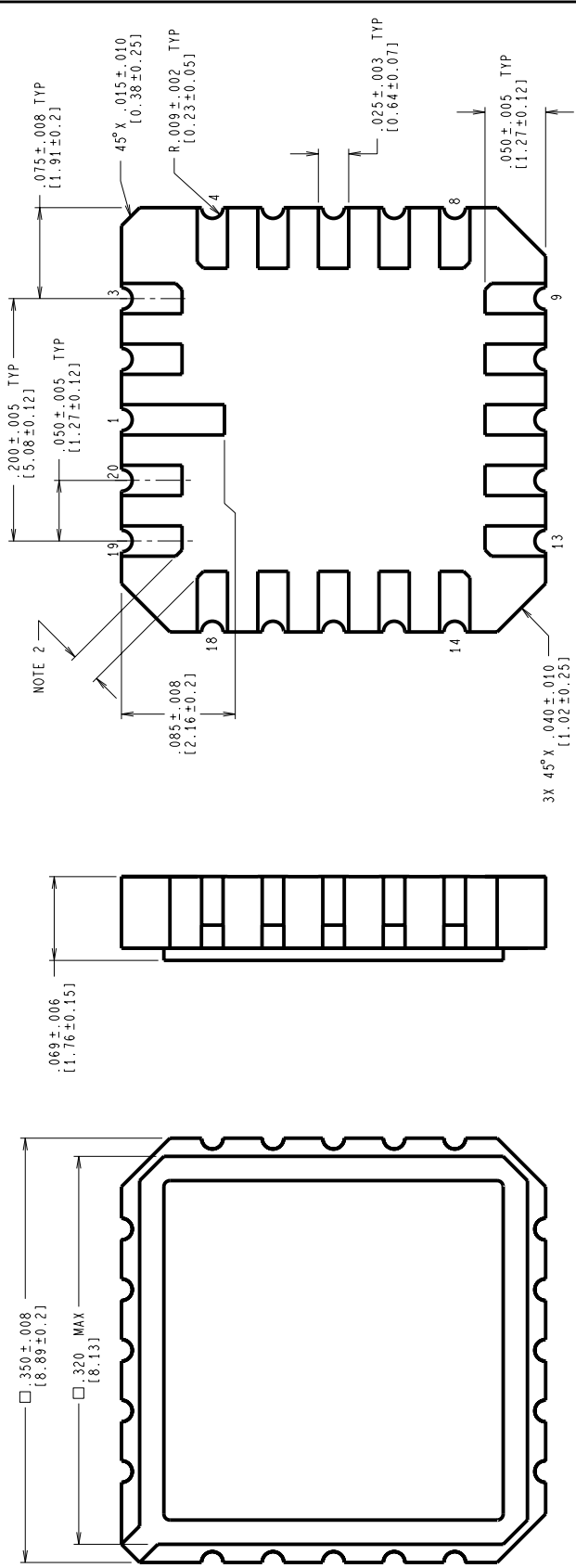
Note 2: For single supply operation, the following conditions apply: $V_+ = 5V$, $V_- = 0V$, $V_{cm} = 2.5V$, $V_{out} = 2.5V$. Vio adjust pins are each connected to V_- to realize maximum output swing. This connection will degrade Vio.

Graphics and Diagrams

GRAPHICS#	DESCRIPTION
05885HRA4	CERDIP (J), 8 LEAD (B/I CKT)
06190HRA3	CERPACK (W, WG), 10LD (B/I CKT)
06191HRA2	LCC (E), TYPE C, 20 TERMINAL (B/I CKT)
E20ARE	LCC (E), TYPE C, 20 TERMINAL(P/P DWG)
J08ARL	CERDIP (J), 8 LEAD (P/P DWG)
P000167A	CERPACK (W), 10 LEAD (PINOUT)
P000168B	LCC (E), 20 LEAD, TYPE C (PINOUT)
P000169A	CERDIP (J), 8 LEAD (PINOUT)
P000259A	CERAMIC SOIC (WG), 10 LEAD (PINOUT)
W10ARG	CERPACK (W), 10 LEAD (P/P DWG)
WG10ARC	CERAMIC SOIC (WG), 10 LEAD (P/P DWG)

See attached graphics following this page.

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
E	REVISE AND REDRAW	10005	02/10/94 DEG/

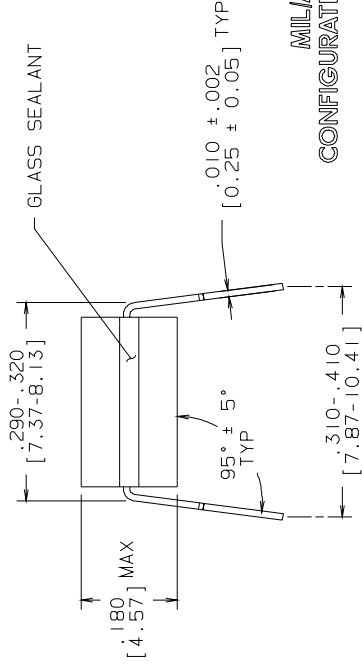
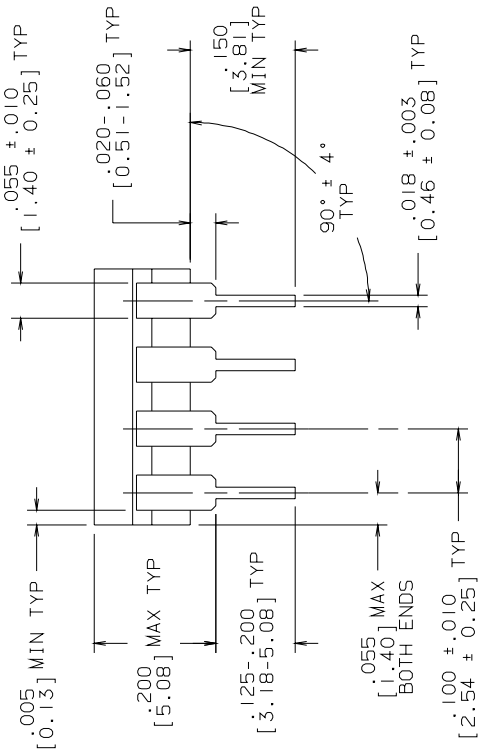
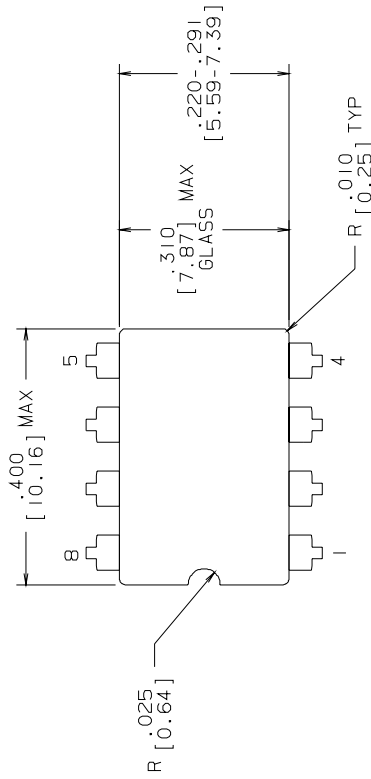


- NOTES: UNLESS OTHERWISE SPECIFIED.
- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 50 MICRONS/12.7 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICRONS/1.27-8.89 MICROMETERS NICKEL.
 - SOLDER DIP. SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.
 - CORNER PADS MAY HAVE A 45° X 0.20 IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE 0.015 IN/0.38mm DIMENSION.
 - REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL/AERO CONFIGURATION CONTROL		NATIONAL SEMICONDUCTOR CORPORATION <small>2300 Semiconductor Drive, Santa Clara, Ca. 95052-8000</small>	
		LEADLESS CHIP CARRIER, TYPE C, 20 TERMINAL	
APPROVALS <small>DRN: Deane Gedy</small> <small>DWG. CHK.</small> <small>ENGR. CHK.</small> <small>APPROVAL</small>	DATE 02/10/94	SCALE N/A	SIZE C
	DRAWING NUMBER MKT-E20A	REV E	SHEET 1 of 1

R E V I S I O N S			
LTR	DESCRIPTION	E. C. N.	DATE
L	REVISE PER CURRENT STD; REDRAW	10002	09/21/93
			BY/APP'D TL/



MILAERO
CONFIGURATION CONTROL
MIL-M-38510
CONFIGURATION CONTROL

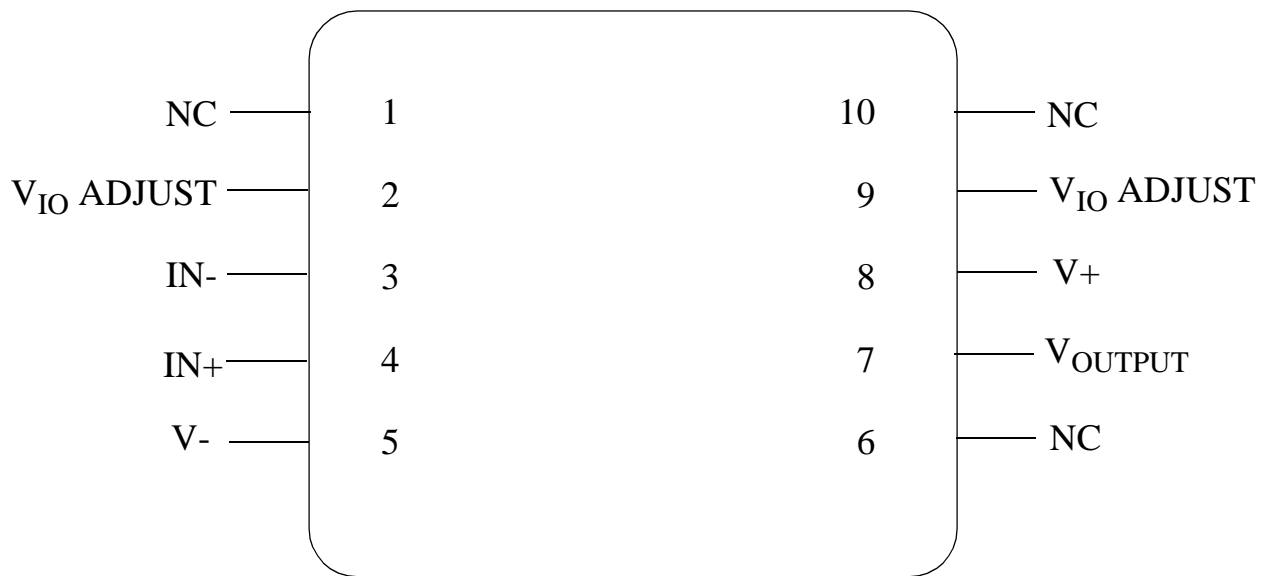
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APPROVALS	DATE
DRAWN T. LEQUANG	09/21/93
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	
 PROJECTION INCH [MM]	
SCALE	DRAWING NUMBER
N/A	B MKT-J08A
DO NOT SCALE DRAWING	SHEET 1 OF 1

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

CERDIP (J),
8 LEAD

NOTES: UNLESS OTHERWISE SPECIFIED

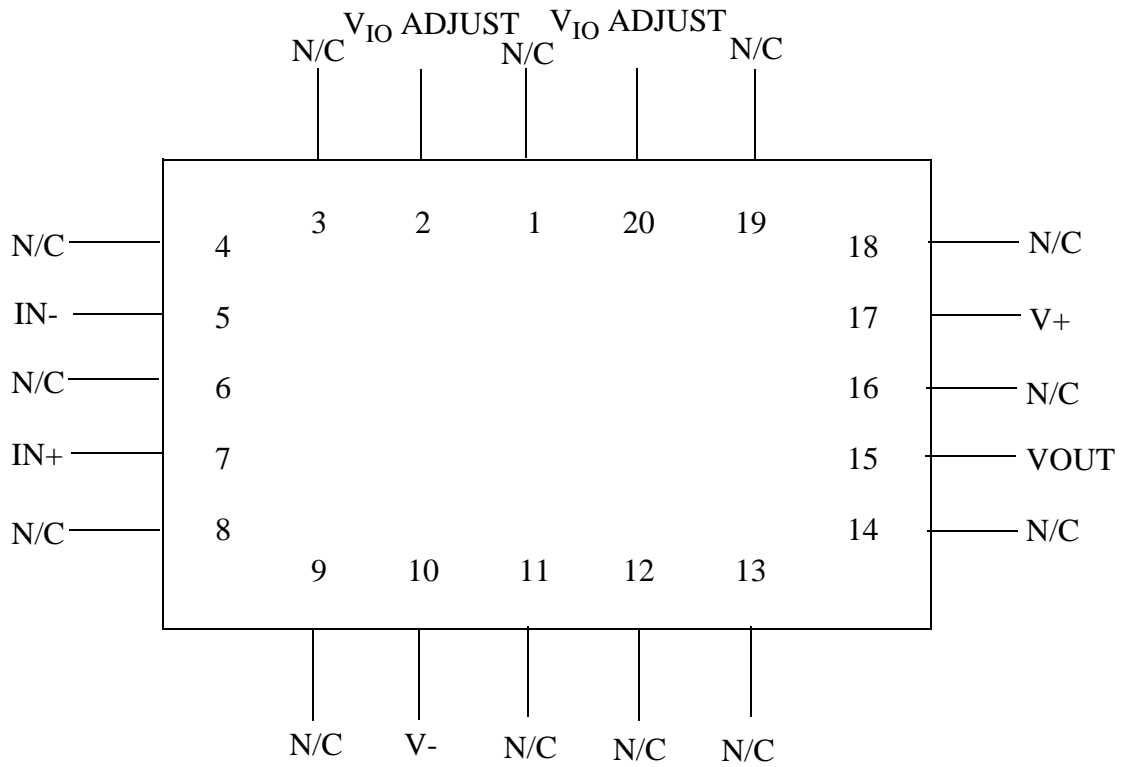
- LEAD FINISH TO BE 200 MICROMETERS / 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- JEDEC REGISTRATION MO-036, VARIATION AA, DATED 04/1981.



LM6161W
10 - LEAD CERPACK
CONNECTION DIAGRAM
TOP VIEW
P000167A



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MIL/AEROSPACE OPERATIONS
2900 SEMICONDUCTOR DRIVE
SANTA CLARA, CA 95050



LM6161E
20 - LEAD LCC
CONNECTION DIAGRAM
TOP VIEW
P000168B



National Semiconductor™

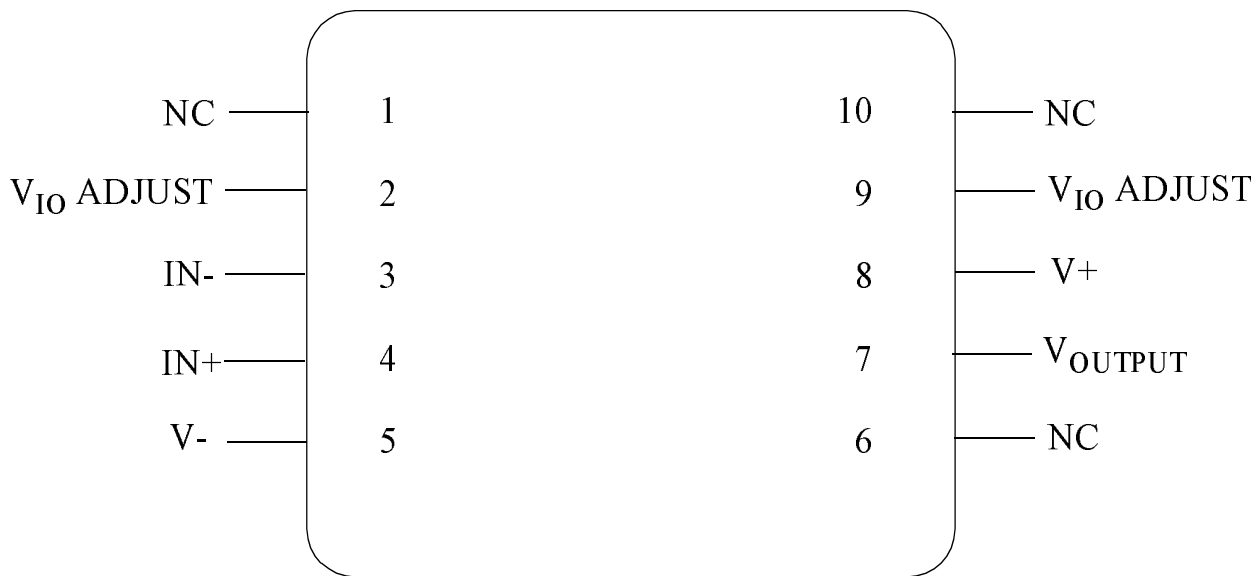
MIL/AEROSPACE OPERATIONS
 2900 SEMICONDUCTOR DRIVE
 SANTA CLARA, CA 95050



LM6161J
8 - LEAD DIP
CONNECTION DIAGRAM
TOP VIEW
P000169A



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SANTA CLARA, CA 95050

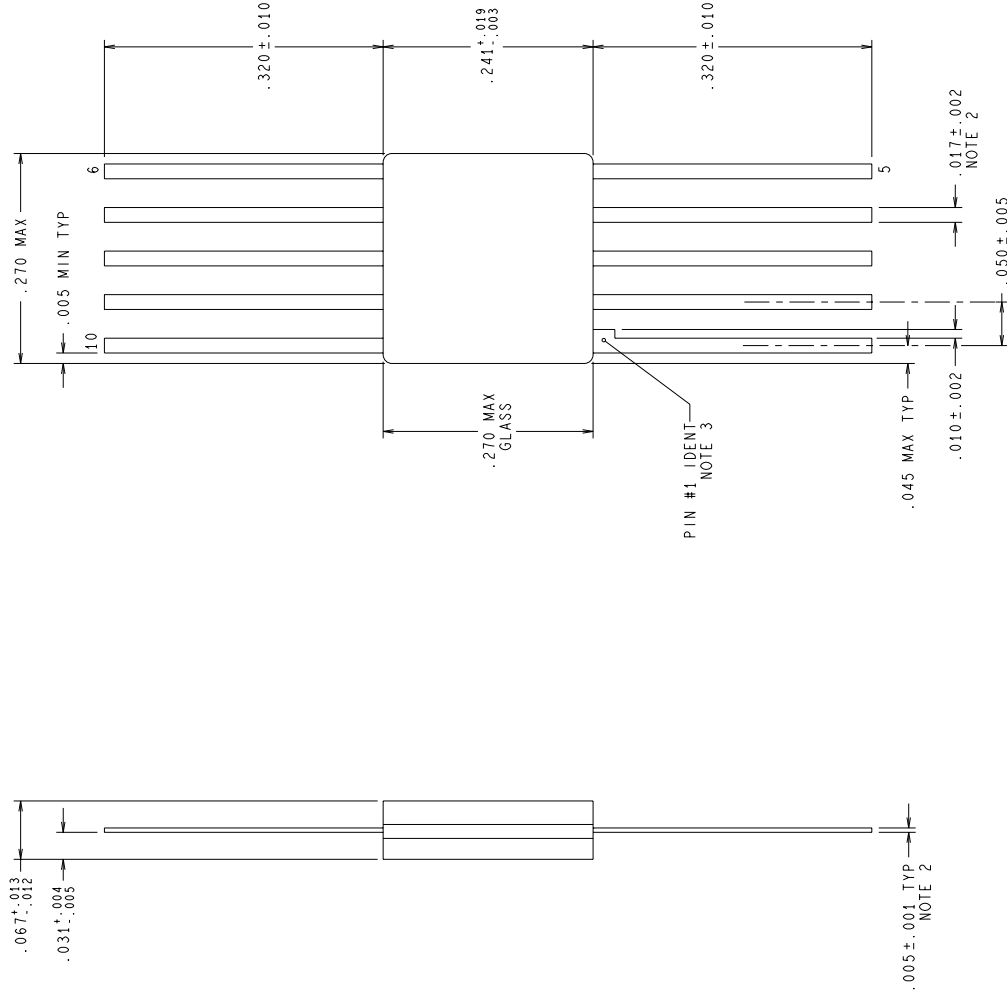


LM6161WG
10 - LEAD CERAMIC SOIC
CONNECTION DIAGRAM
TOP VIEW
P000259A



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2900 SEMICONDUCTOR DRIVE
SANTA CLARA, CA 95050

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
F	REVISE AND REDRAW PER NEW STANDARD.	10510	07/28/94 DEG/AEP
G	.017±.002 WAS .017±.020.	10654	10/21/94 DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-M-38510 TO A MINIMUM THICKNESS OF 200 MICRONS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
- MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
- REFERENCE JEDEC REGISTRATION M0-003, VARIATION AG, DATED 06/01/76.

MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

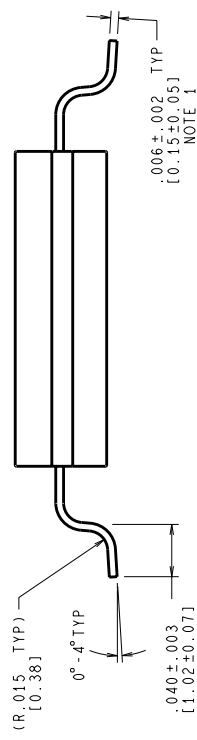
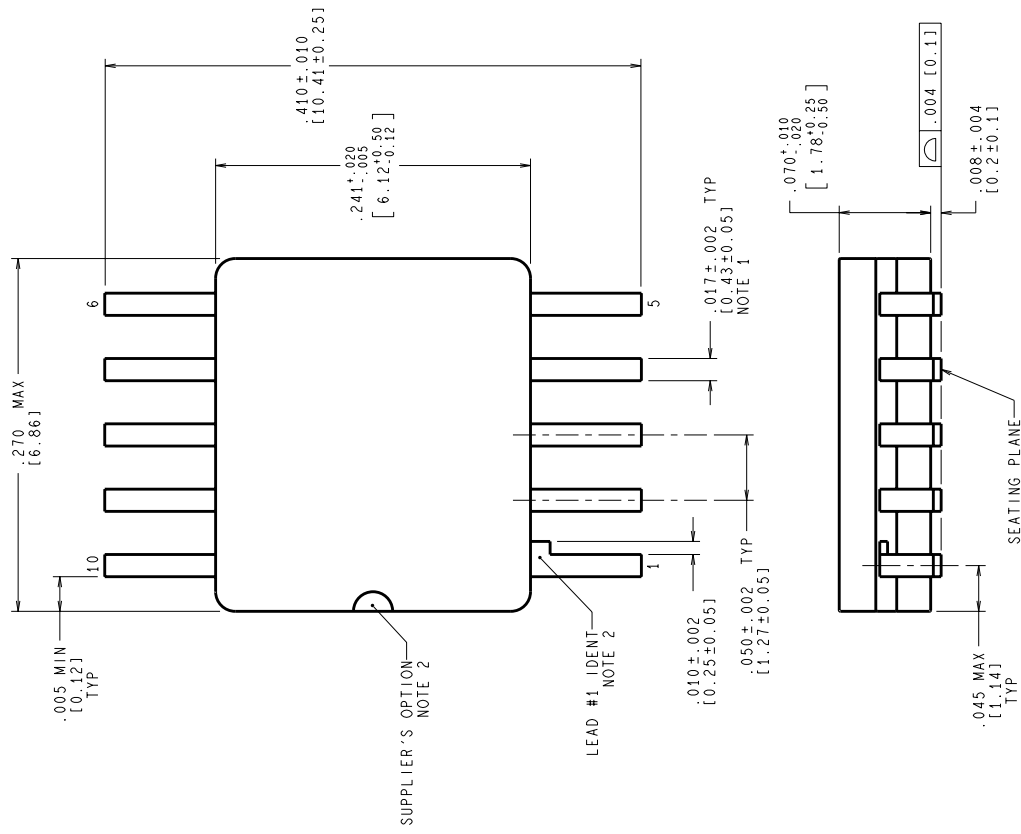
APPROVALS		DATE	
DRWN	<i>D. F. Grady</i>		07/28/94
DTG. CHK.			
ENGR. CHK.			

PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-W10A	G
		DO NOT SCALE DRAWING			

		National Semiconductor	
		2800 Semiconductor dr., Santa Clara, CA 95052-8090	
		CERPACK, 10 LEAD	

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11374	02/29/1996	MS/KH
B	LD PITCH TOL WAS ±.005; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R.006±.002 DIM. .040±.003 WAS .037±.003	11441	04/19/1996	MS/KH
C	R .015(0.38) WAS R .006(0.15)	11838	10/08/1997	TL/



CONTROLLING DIMENSION IS INCH
VALUES IN | ARE MILLIMETERS

MIL-PRF-38535
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICRONS/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
- NO JEDEC REGISTRATION AS OF FEBRUARY 1996.

APPROVALS	DATE	SCALE	SIZE	DRAWING NUMBER	REV
DRN: MARYA SUCHY	02/29/96	N/A	C	(SC)MKT-WG10A	C
DATE: 02/29/96					
ENGR. CHK.					
NATIONAL SEMICONDUCTOR 2800 Semiconductor Dr., Santa Clara, CA 95052-8090					
CERPACK, 10 LEAD, GULL WING					
DO NOT SCALE DRAWING					
SHEET 1 of 1					

Revision History

Rev	ECN #	Rel Date	Originator	Changes
1A1	M0002843	11/23/98	Barbara Lopez	Update MDS: MNL6161-X Rev. 0B0 to MNL6161-X Rev. 1A1. Updated NSID, deleted W-SMD and added WG ID. Added SMD number for WG package. Added WG package to thermal resistance, updated note 6, deleted note 7, added power dissipation limit in Absolute section. Updated Subgroups to match SMD, added note 2 to Electrical section. Added MKT graphic for WG package. Added Pinouts for all packages. Added Burn-In CKT for W and E packages.
2A1	M0003073	11/23/98	Rose Malone	Update MDS: MNL6161-X, Rev. 1A1 to MNL6161-X, Rev. 2A1.